

1 2 3 4 5 6 7 8 9

A

B

C

D

E

F

A

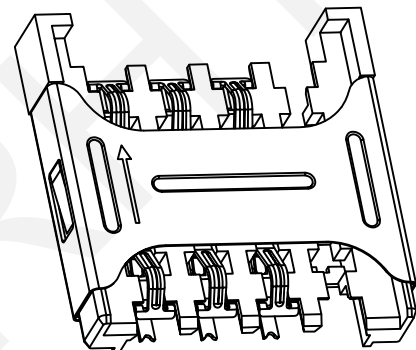
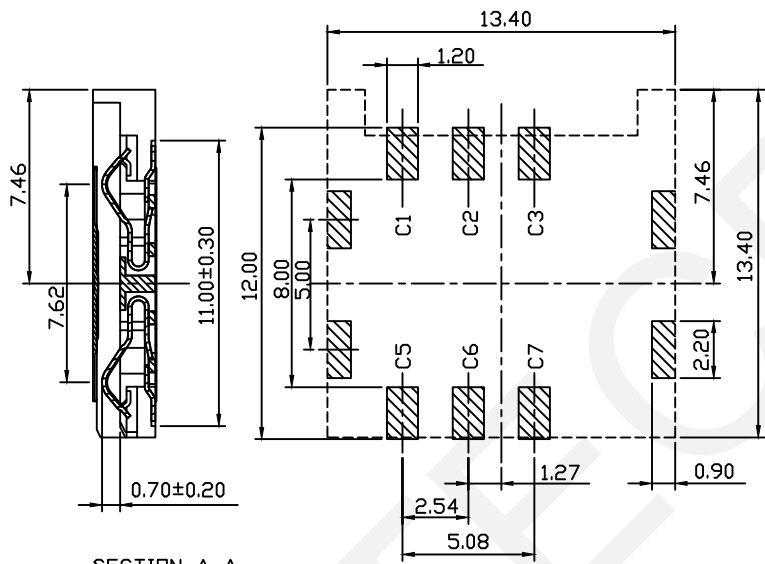
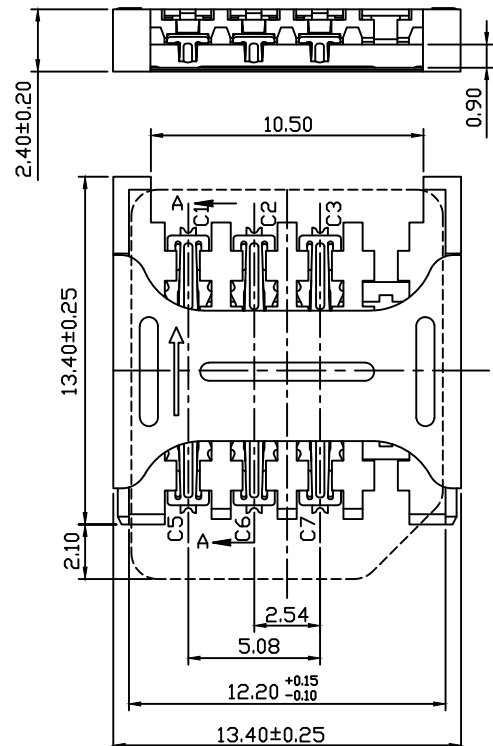
B

C

D

E

F



Material:  
 Base:Hi-Temp Thermoplastic,UL94V-0,Black  
 Data Contact:Copper Alloy,Gold Plated.  
 Shell:Stainless Steel,Gold Plated.

Electrical:  
 1.General Characteristics  
 Dimensions:13.40Lx13.40Wx2.40H mm  
 Weight:Approx0.40±0.1g  
 Durability:5000 Cycles Min.  
 2.Electrical Characteristics  
 Contact Resistance:50mΩ Typical, 100Ω Max.  
 Insulation Resistance:>1000MΩ/500V DC.  
 3.Solderability  
 Vapor Phase:215°C.30Sec.Max.  
 IR reflow:250°C.5Sec.Max.  
 Manual Soldering:370°C.3Sec.Max.  
 4.Environmental Characteristics  
 Operating Temperature:-40°C TO+85°C  
 Operating Humidity:10%~+95%RH

**RHTECP** NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm	SHEET SIZE: A4			SCALE:---
0~3	3~18	18~50	50~120	
±0.12	±0.15	±0.3	±0.5	

DRWN BY PAN  
 CHK'D BY FENG  
 APPR BY ZHAN

Micro SIM Card CONN,6P,H2.4mm,SMD  
 THIRD ANGLE PROJECTION  
 RHTAYIM-044-6P

1 2 3 4 5 6 7 8 9